

BigTwin SuperServer SYS-221BT-HNR

2U 4-Node BigTwin with 6 hot-swap 2.5" NVMe drives per node



More details here

Key Applications

All-Flash NVMe Hyperconverged Infrastructure, Container-as-a-Service; Application Accelerator, High-Performance File System, Diskless HPC Clusters,

Key Features

- Socket E (LGA 4677) support 5th/4th Gen Intel® Xeon® Scalable processors;
- Intel® C741;
- 16 DIMM Slots supporting up to 4TB of memory; ECC RDIMMs up to DDR5-5600;
- 2 PCIe 5.0 x16 (LP) slot; Tool-less support
Internal PCIe 4.0 for 2 x4 M.2 NVMe support onboard
Optional M.2 (22x80) HW RAID1 NVMe Boot Controller via SCC-A2NM2241G3-B1;
- Network connectivity via AIOM (OCP 3.0 compliant);
- 6 hot-swap PCIe 5.0 NVMe 2.5" drives; All Flash NVMe;
- Liquid Cooling Support
4 cooling fans per 2U enclosure, 16K RPM; Shared Cooling Design, Counter-Rotating;
- 3000W Redundant Power Supplies Titanium Level (96%+); Shared Power Design;



- Four **hot-pluggable** systems (nodes) in a 2U form factor. Each node supports Form Factor as following;

2U Rackmount
Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75")
Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")

Processor
Dual Socket E (LGA-4677)
5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors
Supports Intel Xeon CPU Max Series with high bandwidth memory (HBM)
Up to 64C/128T; Up to 320MB Cache per CPU

System Memory
Slot Count: 16 DIMM slots
Max Memory (1DPC): Up to 4TB 5600MT/s ECC DDR5 RDIMM

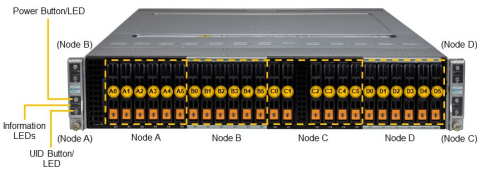
Drive Bays Configuration
Default: Total 6 bay(s)
• 6 front hot-swap 2.5" PCIe 5.0 NVMe drive bay(s)
M.2: 2 M.2 PCIe 4.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)

Expansion Slots
Default
• 2 PCIe 5.0 x16 LP slot(s)

On-Board Devices
Chipset: Intel® C741
Network Connectivity: Via AIOM
IPMI: Support for Intelligent Platform Management Interface v.2.0
IPMI 2.0 with virtual media over LAN and KVM-over-LAN support

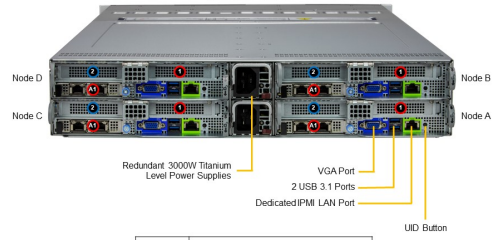
Input / Output
LAN: 1 RJ45 1 GbE Dedicated BMC LAN port(s)
USB: 2 USB 3.0 Gen2 Type-A port(s) (Rear)
Video: 1 VGA port(s)

(Front View – System)



Drive Bay (Node A-B)	Description
① - ②	2 Hot-swap 2.5" PCIe 5.0 NVMe Drive Bays (CPU1)
③ - ④	4 Hot-swap 2.5" PCIe 5.0 NVMe Drive Bays (CPU2)

(Rear View – System)



Slot (Node A-B)	Description
①	PCIe 5.0 x16 A1OM
②	PCIe 5.0 x16 (LP1)
③	PCIe 5.0 x16 (LP1)

CPU1 CPU2

System Cooling	Fans: 4x 16K RPM Counter Rotating 8cm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	3000W Redundant Titanium Level power supplies
System BIOS	BIOS Type: AMI 32MB Flash ROM
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); SuperDoctor® 5; Super Diagnostics Offline ; TAS: Supermicro Thin-Agent Service (TAS); SAA(new!); IPMICFG; SMCIPMITool; IPMIView
PC Health Monitoring	FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment CPU: Monitors for CPU Cores, Chipset Voltages, Memory. 8+4 Phase-switching voltage regulator
Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg) Net Weight: 66.1 lbs (30 kg) Available Color: Black front & silver body
Operating Environment	RoHS Compliant Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X13DET-B
Chassis	CSE-217BQ2-R3K04P